IGBT

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on-state voltage and minimal switching loss. The IGBT is well suited for resonant or soft switching applications. Incorporated into the device is a rugged co-packaged free wheeling diode with a low forward voltage.

Features

- Low Saturation Voltage using Trench with Field Stop Technology
- Low Switching Loss Reduces System Power Dissipation
- Optimized for Low Case Temperature in IH Cooker Application
- Low Gate Charge
- These are Pb-Free Devices

Typical Applications

- Inductive Heating
- Consumer Appliances
- Soft Switching

ABSOLUTE MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|------------------|-------------|------|
| Collector-emitter voltage | V_{CES} | 1200 | V |
| Collector current @ Tc = 25°C @ Tc = 100°C | l _c | 60 30 | Α |
| Pulsed collector current, T _{pulse} limited by T _{Jmax} | I _{CM} | 200 | Α |
| Diode forward current @ Tc = 25°C @ Tc = 100°C | I _F | 60 30 | Α |
| Diode pulsed current, T _{pulse} limited by T _{Jmax} | I _{FM} | 200 | Α |
| Gate-emitter voltage | V_{GE} | ±20 | V |
| Power Dissipation @ Tc = 25°C @ Tc = 100°C | P_D | 192 77 | W |
| Operating junction temperature range | TJ | -55 to +150 | °C |
| Storage temperature range | T _{stg} | -55 to +150 | °C |
| Lead temperature for soldering, 1/8" from case for 5 seconds | T _{SLD} | 260 | °C |

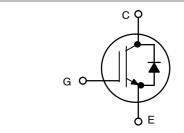
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

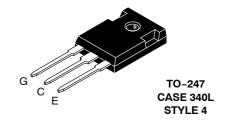


ON Semiconductor®

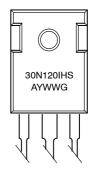
http://onsemi.com

30 A, 1200 V V_{CEsat} = 2.00 V E_{off} = 1.0 mJ





MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

| Device | Package | Shipping |
|-----------------|---------------------|-----------------|
| NGTB30N120IHSWG | TO-247 (Pb-Free) | 30 Units / Rail |

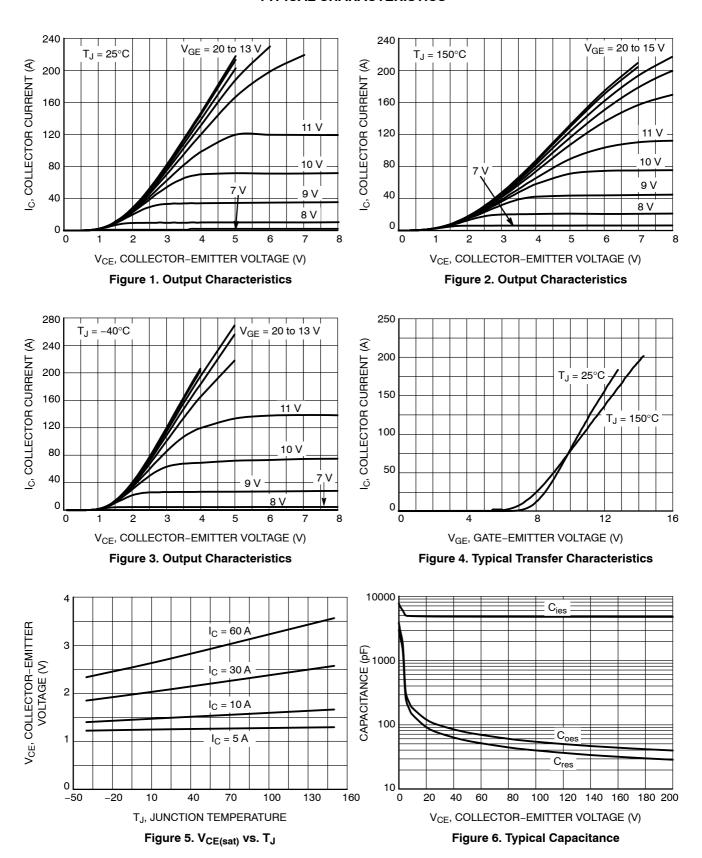
THERMAL CHARACTERISTICS

| Rating | Symbol | Value | Unit |
|--|---------------|-------|------|
| Thermal resistance junction-to-case, for IGBT | $R_{	hetaJC}$ | 0.65 | °C/W |
| Thermal resistance junction-to-case, for Diode | $R_{	hetaJC}$ | 2.0 | °C/W |
| Thermal resistance junction-to-ambient | $R_{	hetaJA}$ | 40 | °C/W |

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

| Parameter | Test Conditions | Symbol | Min | Тур | Max | Unit | |
|---|--|----------------------|-------------------|------------|------------|------|--|
| STATIC CHARACTERISTIC | | | | | | | |
| Collector-emitter breakdown voltage, gate-emitter short-circuited | $V_{GE} = 0 \text{ V, I}_{C} = 500 \mu\text{A}$ | V _{(BR)CES} | 1200 | _ | _ | V | |
| Collector-emitter saturation voltage | V _{GE} = 15 V, I _C = 30 A V _{GE} = 15 V, I _C = 30 A, T _J = 150°C | V _{CEsat} | - - | 2.0 2.6 | 2.4 - | V | |
| Gate-emitter threshold voltage | $V_{GE} = V_{CE}, I_{C} = 250 \mu A$ | V _{GE(th)} | 4.5 | 5.5 | 6.5 | V | |
| Collector-emitter cut-off current, gate- emitter short-circuited | V _{GE} = 0 V, V _{CE} = 1200 V V _{GE} = 0 V, V _{CE} = 1200 V, T _{J =} 150°C | I _{CES} | - - | - - | 0.5 2.0 | mA | |
| Gate leakage current, collector-emitter short-circuited | V _{GE} = 20 V, V _{CE} = 0 V | I _{GES} | - | - | 100 | nA | |
| DYNAMIC CHARACTERISTIC | DYNAMIC CHARACTERISTIC | | | | | | |
| Input capacitance | | C _{ies} | - | 5300 | - | pF | |
| Output capacitance | $V_{CE} = 20 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$ | C _{oes} | - | 125 | - | | |
| Reverse transfer capacitance | | C _{res} | - | 95 | _ | | |
| Gate charge total | | Q_g | - | 220 | _ | nC | |
| Gate to emitter charge | V _{CE} = 600 V, I _C = 30 A, V _{GE} = 15 V | Q _{ge} | - | 42 | - | | |
| Gate to collector charge | | Q _{gc} | - | 95 | - | | |
| SWITCHING CHARACTERISTIC, INDUCT | TIVE LOAD | | | | | | |
| Turn-off delay time | T _J = 25°C | t _{d(off)} | - | 210 | _ | ns | |
| Fall time | $V_{CC} = 600 \text{ V}, I_{C} = 30 \text{ A}$ $R_{\alpha} = 10 \Omega$ | t _f | - | 140 | - | | |
| Turn-off switching loss | V _{GE} = 0 V/ 15V | E _{off} | - | 1.0 | - | mJ | |
| Turn-off delay time | T _J = 125°C | t _{d(off)} | - | 215 | - | ns | |
| Fall time | $V_{CC} = 600 \text{ V}, I_{C} = 30 \text{ A}$ $R_{g} = 10 \Omega$ | t _f | - | 175 | - | | |
| Turn-off switching loss | V _{GE} = 0 V/ 15V | E _{off} | - | 1.8 | - | mJ | |
| DIODE CHARACTERISTIC | | | | | | | |
| Forward voltage | V _{GE} = 0 V, I _F = 30 A V _{GE} = 0 V, I _F = 30 A, T _J = 150°C | V _F | - - | 1.8 2.0 | 2.0 - | V | |

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

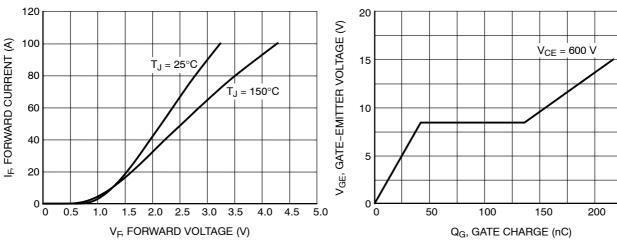


Figure 7. Diode Forward Characteristics

Figure 8. Typical Gate Charge

250

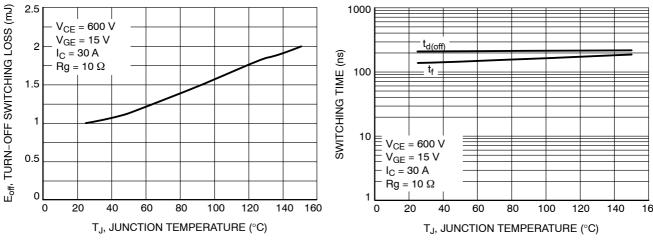


Figure 9. Energy Loss vs. Temperature

Figure 10. Switching Time vs. Temperature

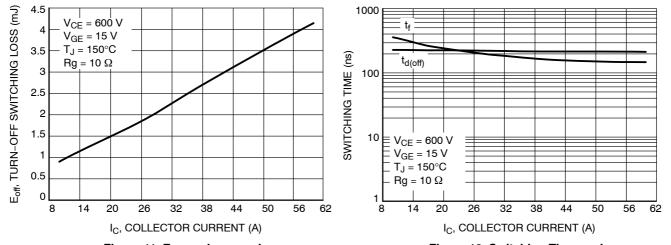
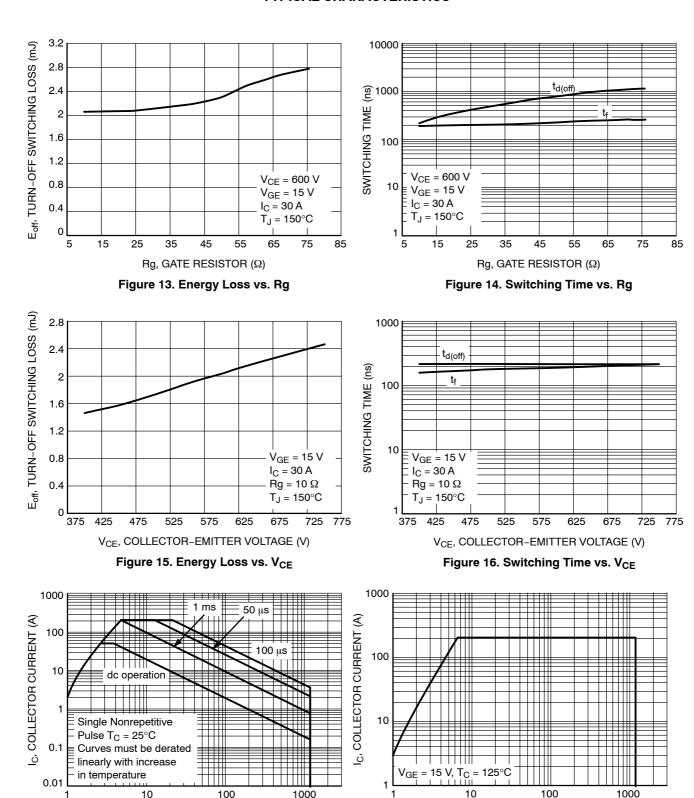


Figure 11. Energy Loss vs. $I_{\rm C}$

Figure 12. Switching Time vs. $I_{\mathbb{C}}$

TYPICAL CHARACTERISTICS



V_{CE}, COLLECTOR-EMITTER VOLTAGE (V) Figure 17. Safe Operating Area

V_{CE}, COLLECTOR-EMITTER VOLTAGE (V)

Figure 18. Reverse Bias Safe Operating Area

TYPICAL CHARACTERISTICS

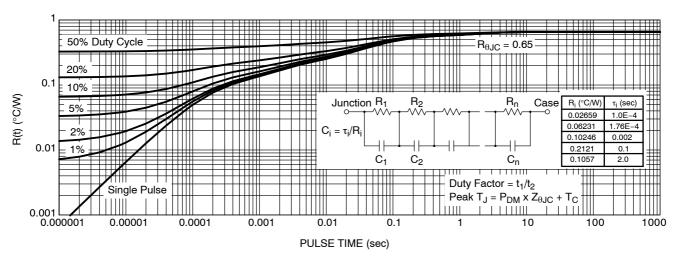


Figure 19. IGBT Transient Thermal Impedance

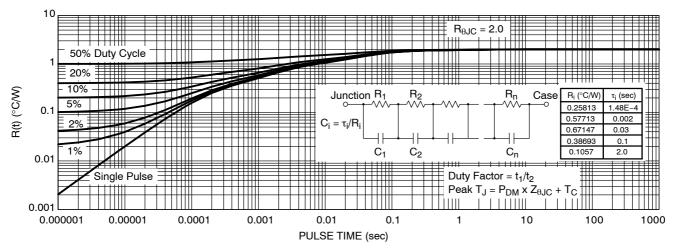


Figure 20. Diode Transient Thermal Impedance

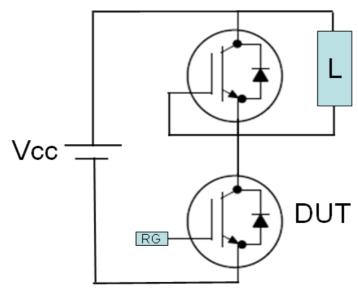


Figure 21. Test Circuit for Switching Characteristics

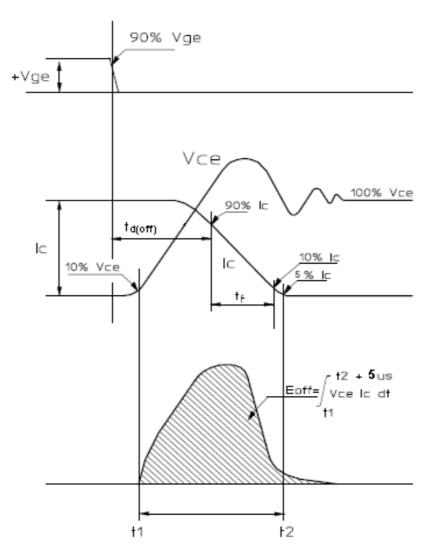
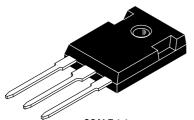


Figure 22. Definition of Turn Off Waveform





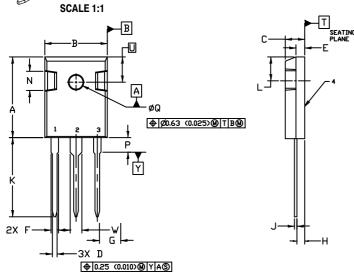
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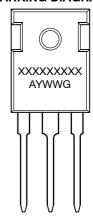
NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER

| | MILLIMETERS | | INC | HES | |
|-----|-------------|-------|-------|-----------|--|
| DIM | MIN. | MAX. | MIN. | MAX. | |
| Α | 20.32 | 21.08 | 0.800 | 0.830 | |
| В | 15.75 | 16.26 | 0.620 | 0.640 | |
| С | 4.70 | 5.30 | 0.185 | 0.209 | |
| D | 1.00 | 1.40 | 0.040 | 0.055 | |
| Ε | 1.90 | 2.60 | 0.075 | 0.102 | |
| F | 1.65 | 2.13 | 0.065 | 0.084 | |
| G | 5.45 BSC | | 0.215 | 0.215 BSC | |
| Н | 1.50 | 2.49 | 0.059 | 0.098 | |
| J | 0.40 | 0.80 | 0.016 | 0.031 | |
| К | 19.81 | 20.83 | 0.780 | 0.820 | |
| L | 5.40 | 6.20 | 0.212 | 0.244 | |
| N | 4.32 | 5.49 | 0.170 | 0.216 | |
| Р | | 4.50 | | 0.177 | |
| Q | 3.55 | 3.65 | 0.140 | 0.144 | |
| U | 6.15 BSC | | 0.242 | BSC | |
| W | 2.87 | 3.12 | 0.113 | 0.123 | |



GENERIC MARKING DIAGRAM*



 STYLE 1:
 STYLE 2:

 PIN 1. GATE
 PIN 1. ANODE

 2. DRAIN
 2. CATHODE (S)

 3. SOURCE
 3. ANODE 2

 4. DRAIN
 4. CATHODES (S)

STYLE 3: PIN 1. BASE 2. COLLE 3. EMITT 4. COLLE

3: STYLE 4:
11. BASE PIN 1. GATE
2. COLLECTOR 2. COLLECTOR
3. EMITTER
4. COLLECTOR 4. COLLECTOR

XXXXX = Specific Device Code A = Assembly Location

Y = Year
WW = Work Week
G = Pb-Free Package

 STYLE 5:
 STYLE 6:

 PIN 1. CATHODE
 PIN 1. MAIN TERMINAL 1

 2. ANODE
 2. MAIN TERMINAL 2

 3. GATE
 3. GATE

 4. ANODE
 4. MAIN TERMINAL 2

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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 VS-CPV364M4KPBF
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 NGTG40N120FL2WG
 RJH60F3DPQ-A0#T0

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 APT20GT60BRG
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 IXA30RG1200DHGLB

 IXA40RG1200DHGLB
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 NTE3320
 IHFW40N65R5SXKSA1
 APT70GR120J
 APT35GP120JDQ2

 IKZA40N65RH5XKSA1
 IKFW75N65ES5XKSA1
 IKFW50N65ES5XKSA1
 IKFW50N65EH5XKSA1
 IKFW40N65ES5XKSA1

 IKFW60N65ES5XKSA1
 IMBG120R090M1HXTMA1
 IMBG120R220M1HXTMA1
 XD15H120CX1
 XD25H120CX0
 XP15PJS120CL1B1

 IGW30N60H3FKSA1
 STGWA8M120DF3
 IGW08T120FKSA1
 IGW75N60H3FKSA1
 HGTG40N60B3
 FGH60N60SMD_F085

 FGH75T65UPD
 STGWA15H120F2
 IKA10N60TXKSA1
 IHW20N120R5XKSA1
 RJH60D2DPP-M0#T2
 IKP20N60TXKSA1

 IHW20N65R5XKSA1
 IDW40E65D2FKSA1